



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



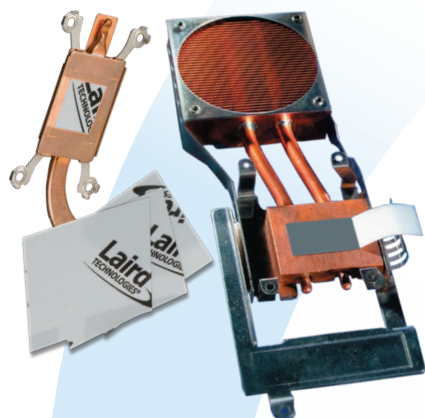
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Tpcm™ 670 is a high performance, inherently tacky, easy to rework phase change thermal interface material. Developed specifically to meet the high thermal conductivity and low thermal resistance requirements of Intel® mobile processors. Tpcm 670 is optimized for multi-core and general CPU and GPU processors including Intel's Penryn Quad-Core mobile processor.

FEATURES AND BENEFITS

- Minimizes contact thermal resistance by filling the microscopic irregularities of the components it contacts. Begins to soften and flow at approximately 48°C.
- Designed to minimize migration (pump out) at CPU operating temperatures using a unique material formulation that softens, but does not fully change phase.
- Naturally tacky at room temperature, requiring no adhesive.
- Heat sink preheating not required.
- Supplied on tabbed liners for easy manual or automatic application.
- Exceptionally high reliability.
- Available with Laird Technologies easy release DF (patent pending) layer. DF (patent pending) minimizes the force required to disassemble after burn-in while still maintaining the highest possible thermal performance and exceptional reliability.

| PROPERTIES | Tpcm™ 670 | *Tpcm™ 670DF | TEST METHOD |
|---|------------------------------|---|-------------------------------------|
| Color | Grey | | Visual |
| Thickness, inches (mm) | 0.008" (0.20) 0.010 (.25) | 0.005 (0.125) 0.008" (0.20) 0.010 (.25) | |
| Thickness Tolerance, inches (mm) | +/-0.001" (0.025) | | |
| Construction & Composition | Non-reinforced Film | | |
| Specific Gravity, g/cc | 2.50 | | Helium Pycnometer |
| Shelf Life | 1 year | | |
| Operating Temperature Range, °C | -40 to 125°C | | |
| Phase Change Softening Range, °C | 45 to 70°C | | |
| Thermal Conductivity, W/mK | 4.3 | | Hot Disk Thermal Constants Analyzer |
| Thermal Resistance | | | |
| Outer core, 25 micron die height offset, °C-cm²/W, (°C-mm²/W) | 0.117 (11.7) | | Intel Mobile TIM Tester |
| 50 psi °C-in²/ W | 0.010 | 0.025 | ASTM D5470 (modified) |
| 345 Kpa, °C-cm²/W | 0.065 | 0.161 | ASTM D5470 (modified) |

* patent pending

global solutions: local support™

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

THR-DS-Tpcm-670-670DF 0910

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2010 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trade marks or registered trade marks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.